LSI LOGIC®

4420 ArrowsWest Drive Colorado Springs, CO 80907

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To: T10 Technical Committee

From: John Lohmeyer, LSI Logic Principal Member of T10

Subj: Proposal to change MSE high-impedance current specification in SPI-3

The May '99 SPI-3 working group requested that I develop a written proposal regarding relaxing the High Z input characteristics of MSE devices (i.e., their input characteristics when they are not driving the bus). After posting rev 0, I received some suggestions for improvements from Claude Pattein via email. I've included those changes and a couple editorial changes in rev 1 of this proposal. I propose the following changes be made to SPI-3 rev 7:

Add a second sentence to the paragraph immediately above Table 15:

In addition to the device electrical requirements defined in the remaining subclauses of this clause <u>SCSI</u> devices shall meet the requirements specified in table 15 and table 16 at the device connector. <u>The</u> requirements in table 16 shall apply to both powered and unpowered devices.

Modify table 16 as shown:

Table 16 - Input current requirements at the device connector for lines not being driven by the device

Value	Maximum	Notes
MSE current magnitude	<u>See figure <new></new></u>	Measured from + or - signal $0 < V_{IN} < 4,1$ V to local ground for each signal pin.
LVD current magnitude	<u>+</u> 20 μA D.C.	Measured from + or - signal $0 \le V_{IN} \le 2,5$ V to local ground for each signal pin.

Note: I added the "0 <" to the second row above. It appears that this was inadvertently left out.

Add a new figure under table 16:

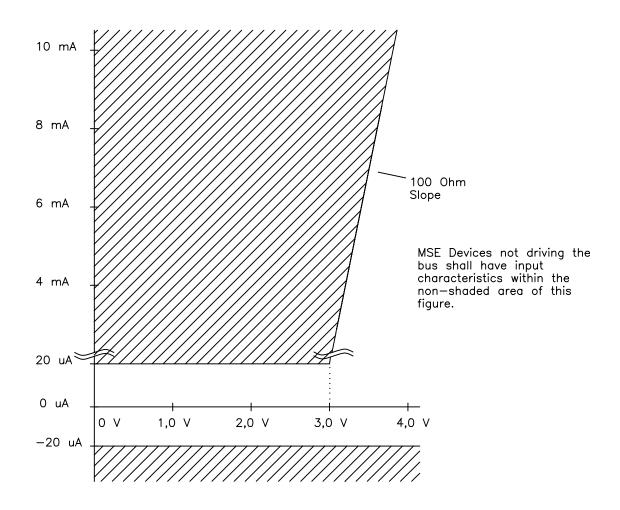


Figure <new> - MSE device high-impedance input characteristics

After re-reading annex A and table 16, I've come to the conclusion that no changes are needed in annex A because it only applies to LVD mode and LVD mode is not tested above 2,5 V (per row 2 of table 16).